



FNAL Production Experience

J. Incandela

CMS Tracker Week

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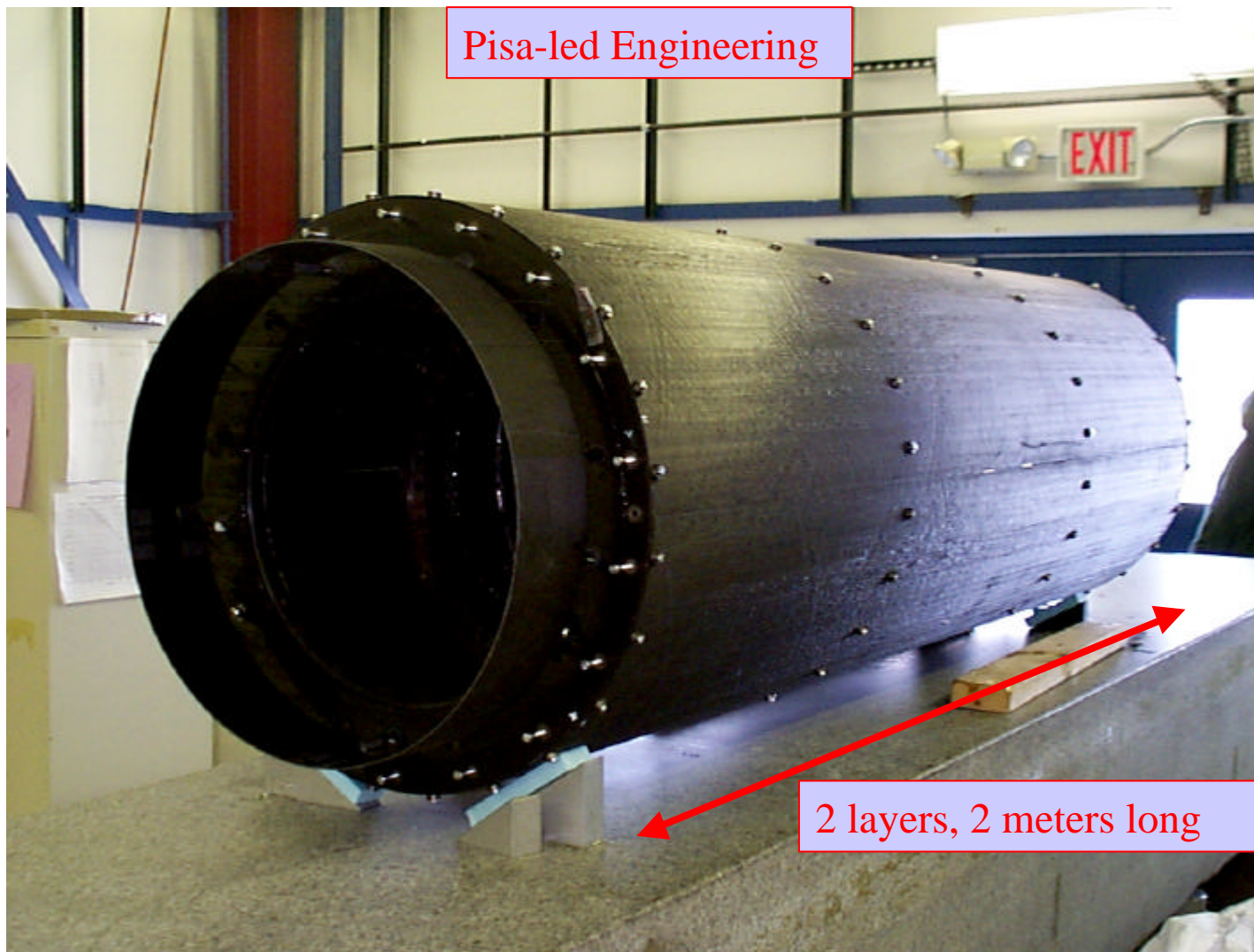


Outline

- Similarity of CDF ISL to CMS tracker
- Recent CDF ISL Production Experience at FNAL
(A. Affolder, S. Baroiant, J. Goldstein, C.Hill, and D. Stuart)
 - Production rates
 - Testing results
 - Mechanical quality
 - Damage
- Expectation for CMS

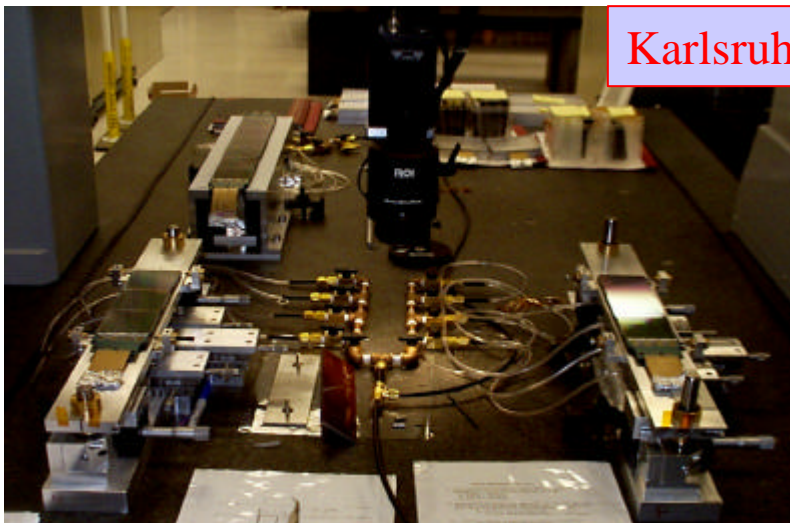


CDF ISL

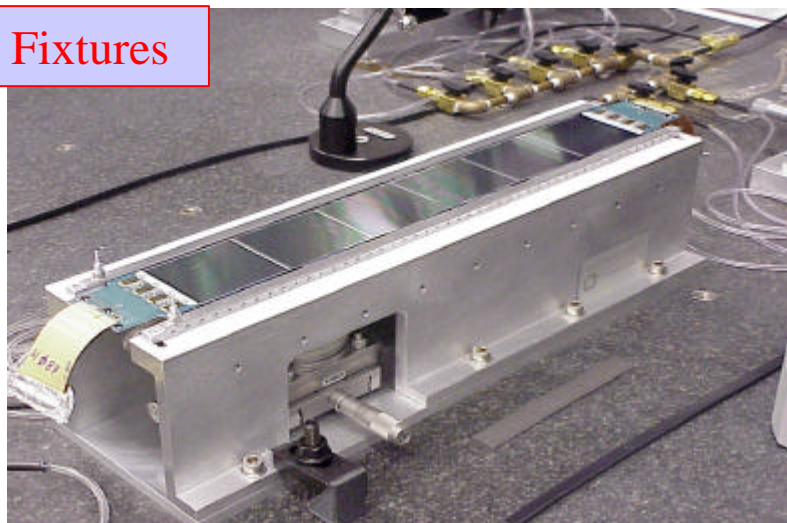




ISL Module Assembly at FNAL



Karlsruhe Fixtures

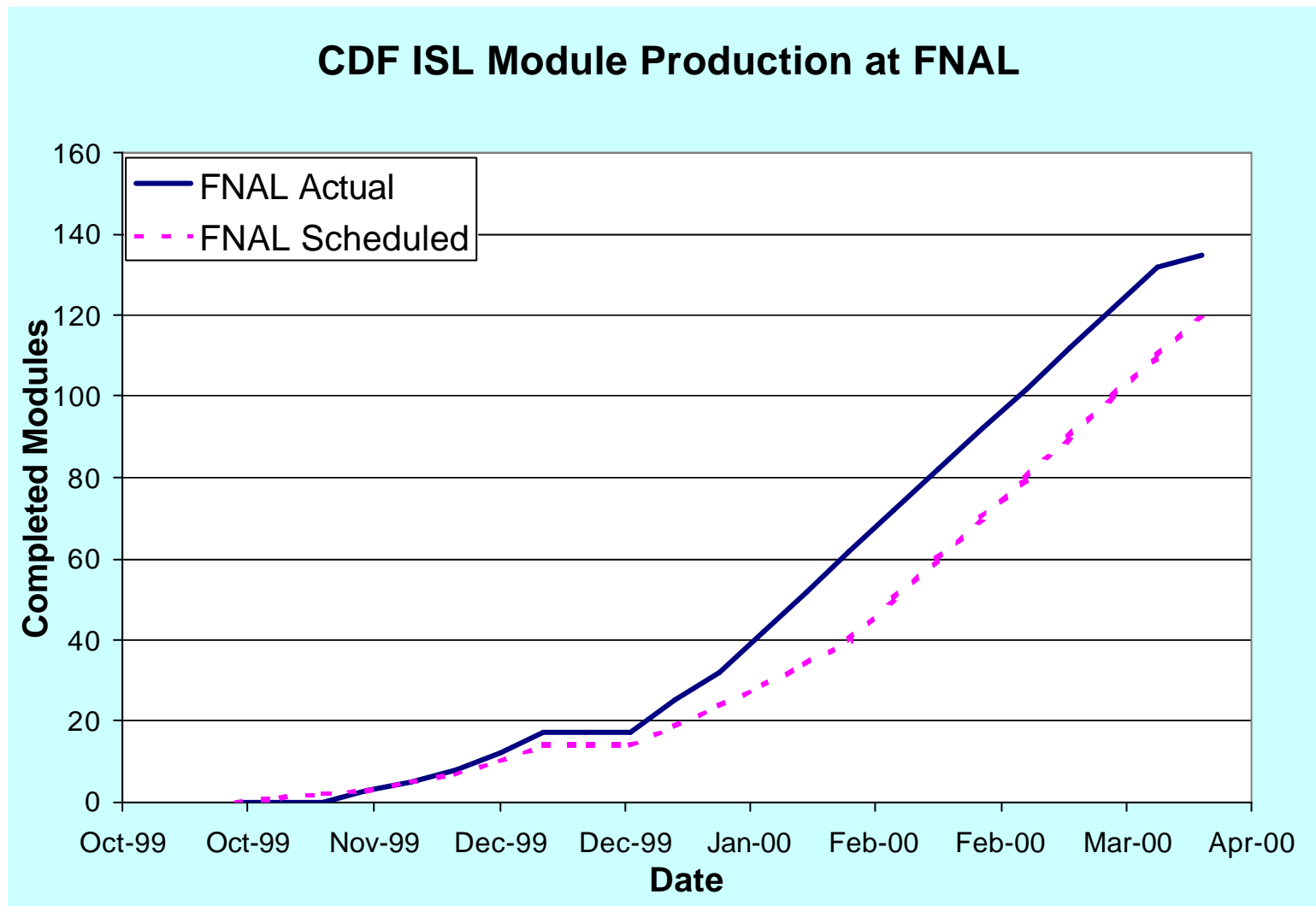


K&S 8090

- ISL half modules
 - 3 double-sided sensors
 - 1 double-sided hybrid w/pitch adapters
 - 512 channels/side
 - 4096 total wirebonds



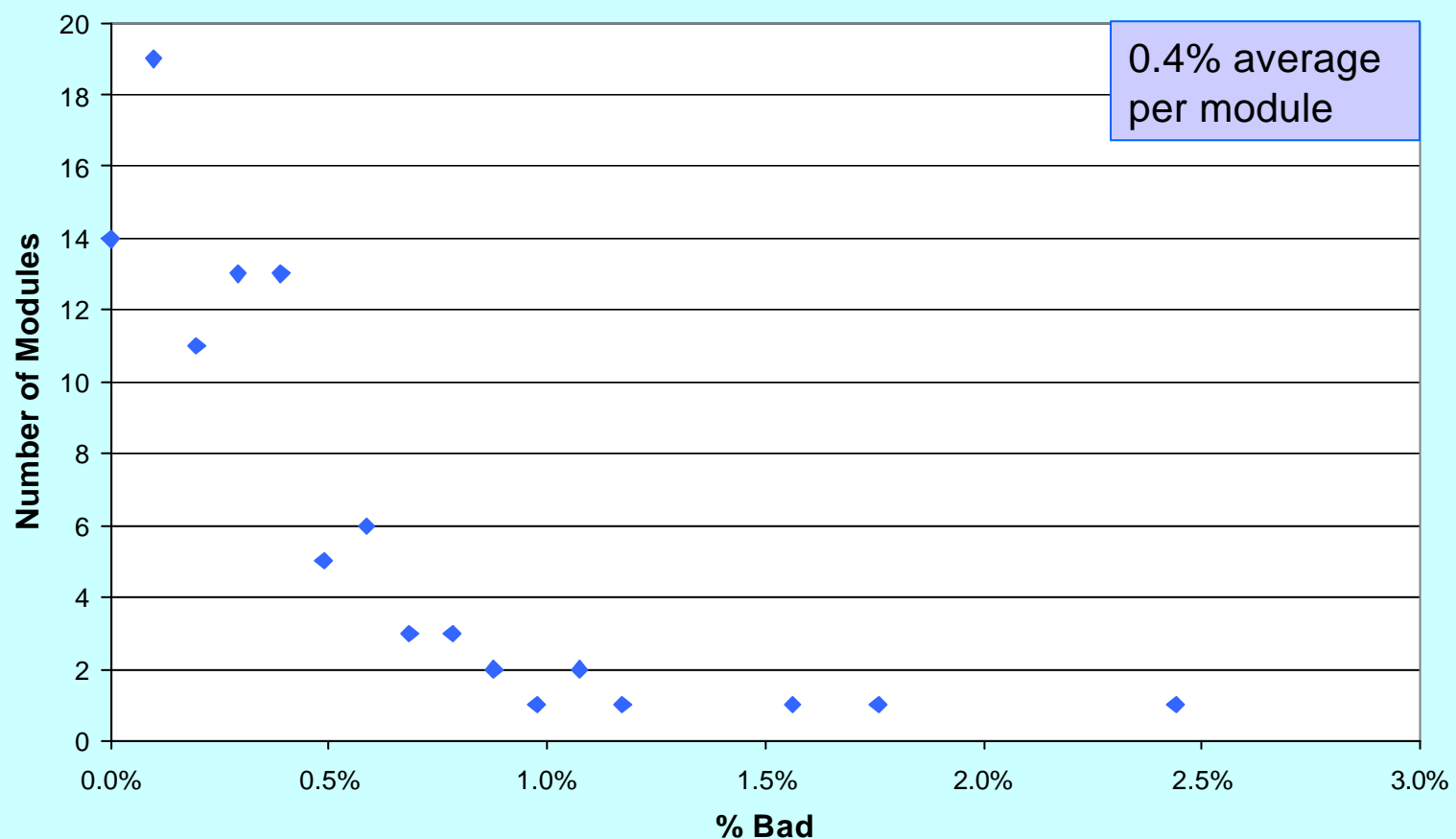
CDF ISL Production





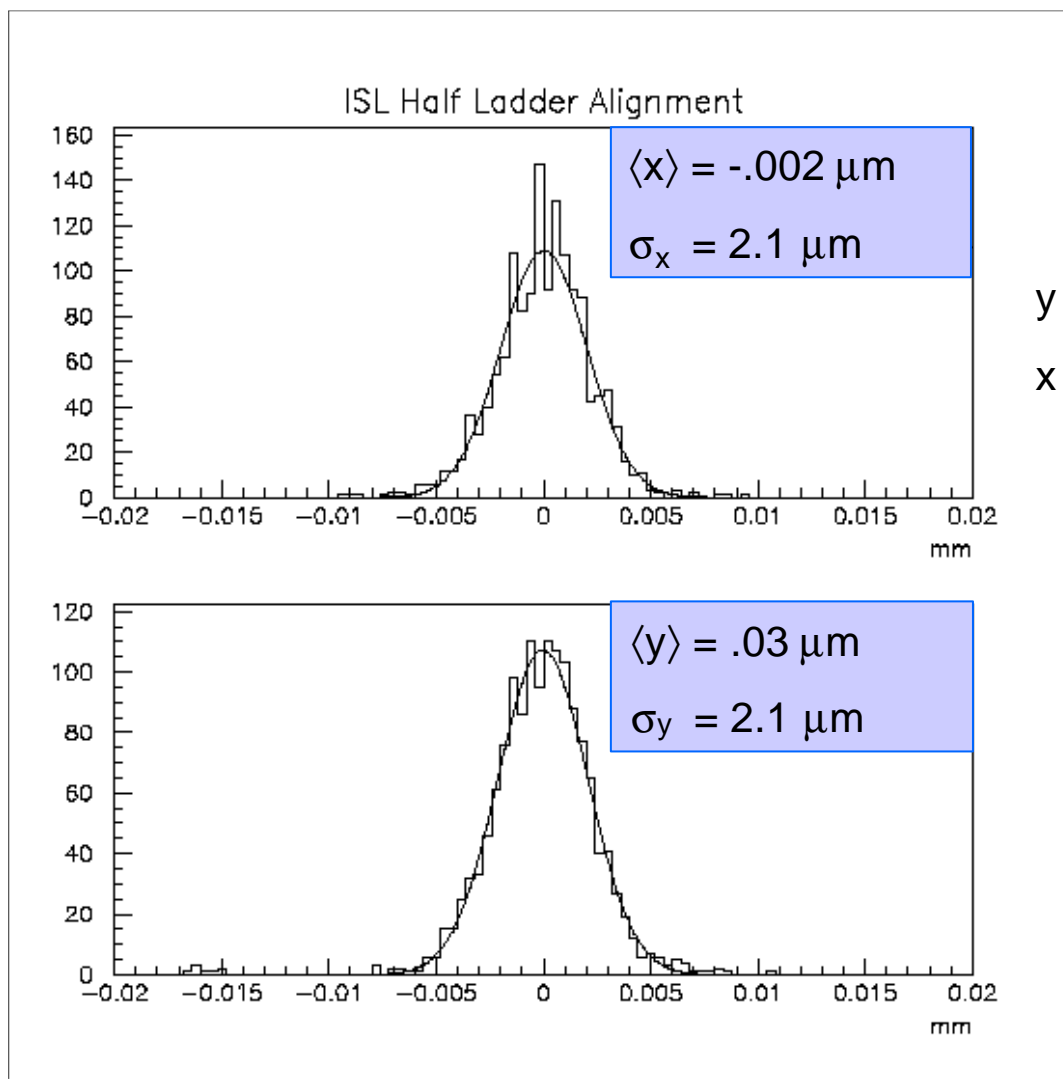
Low Production Damage

% Bad Strips Formed During Module Production





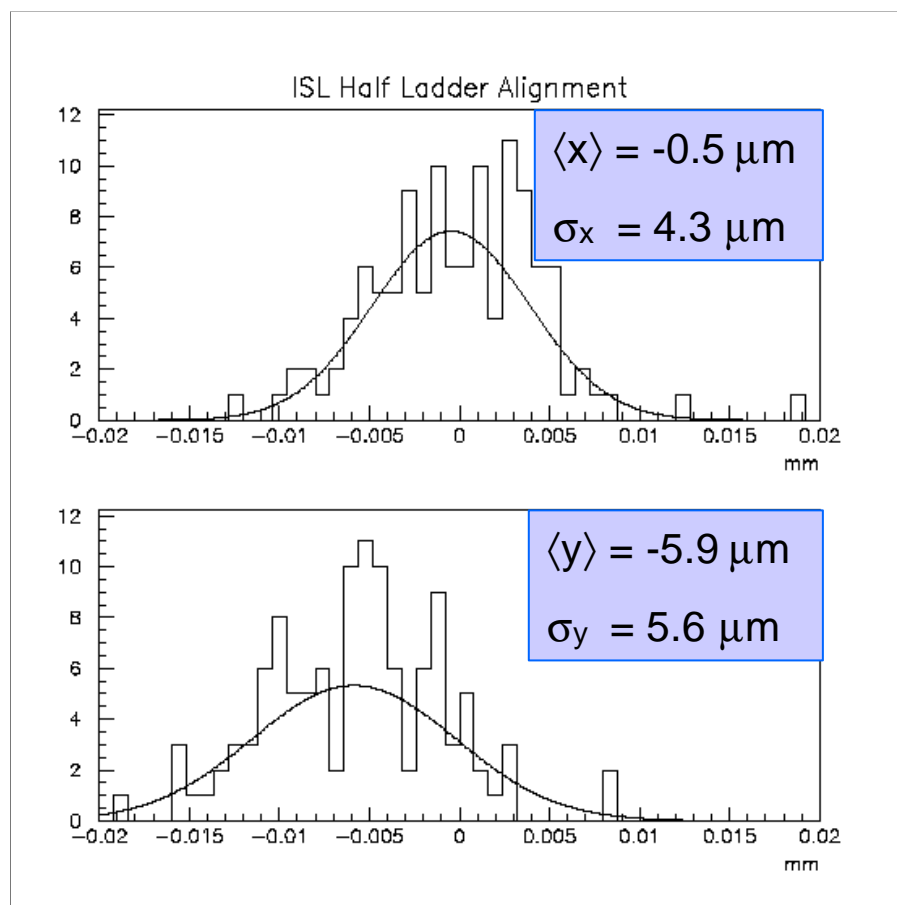
Silicon Alignments



y is orthogonal to strips
x is parallel to strips



Si-to-Mounting Hole

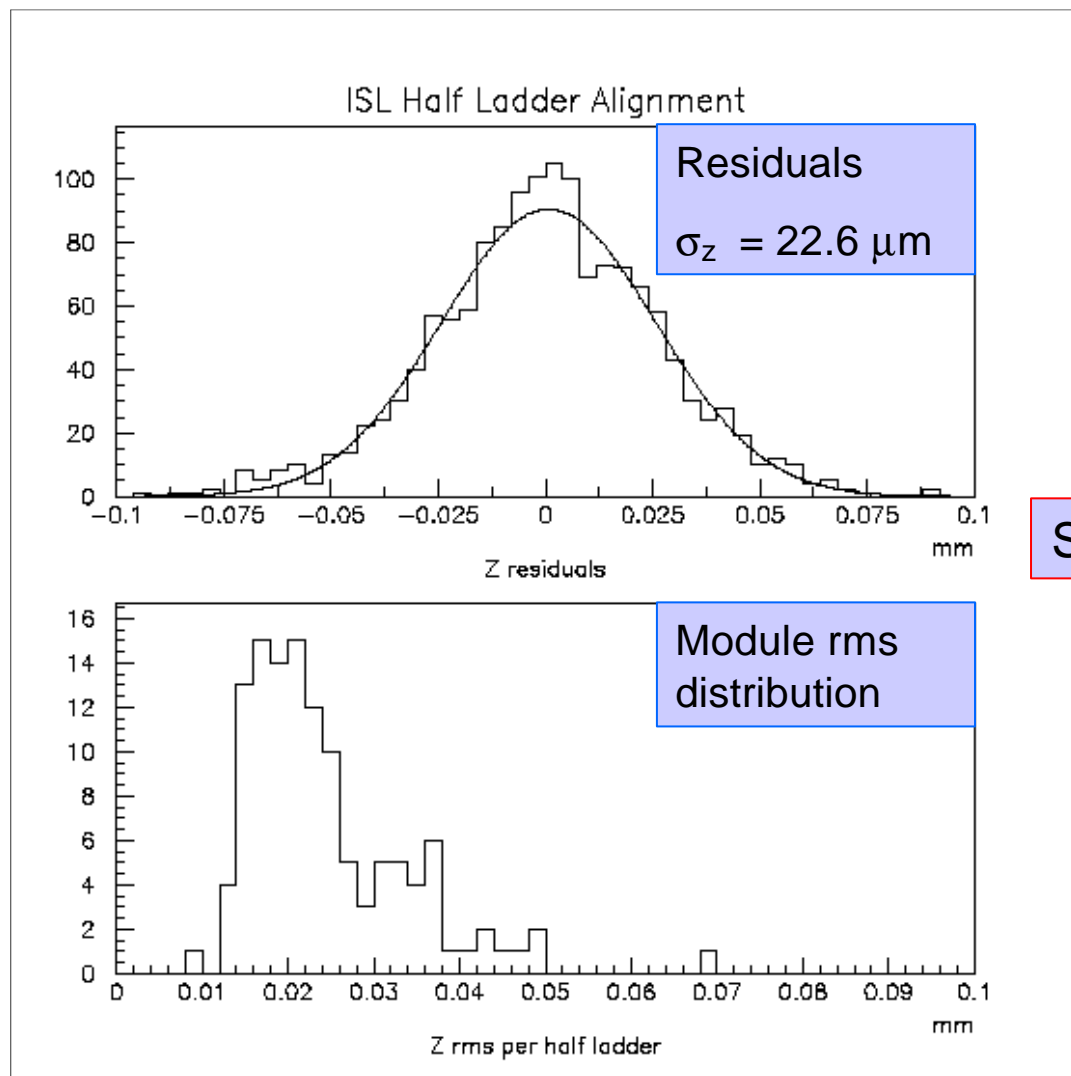


Mounting Hole Alignment

- Factors into alignment in the final assembly.
- Use one machine to build module (B&S CMM) and another to check it (OGP)
 - y-offset indicates the systematic uncertainty.
 - different lighting (non-uniform)
 - inherently difficult to measure a hole location.
 - Spec. is $\pm 25 \mu\text{m}$



Flatness



Spec. 100 μm



Damage Rates

- Silicon Loss rates (~420 HPK DS sensors used)
 - 1 damaged during probing
 - 6 lost in module construction (see below)
- Module Loss rates (~140 manufactured modules)
 - Two modules irretrievably damaged by wirebonder
 - new machine had an unexpected referencing feature
 - no longer an issue
 - no other damage
 - None lost in testing or burn-in



Test Procedures

- Test parts at each stage of module construction
 - Ensure no loss of functionality of SVX3D chips
 - Identify damage due to construction
 - (e.g. pinholes created in fabrication/wire-bonding)
 - Characterize performance
- “Burn in” parts to test long-term reliability
 - Hybrids are burned in for 72 hours continuous operation
 - Half-ladders are burned in for 48 hours
 - Bias Voltage cycled every 6 hours from 0V to 50% over depletion
 - Thermally cycled every 6 hours over 20 degrees
- Testing should be fast, efficient, and accurate
 - Testing is procedural, presentation of results is automated



Procedure

- Hybrids burned in at LBL, then shipped to FNAL
- Tested upon arrival at FNAL
- Pitch-adaptor is bonded and the hybrid is re-tested
- Silicon is bonded, pinholes identified, removed from readout
- Half-ladder is tested
 - Operating voltage determined
 - Occupancy and efficiency estimated from measured quantities
 - Ladder graded (grade A is $> 94\%$ efficiency, $< 2\%$ occupancy)
- Half-ladders burned in then mated to make modules
 - mates are selected to match in occupancy and efficiency
- Modules tested, put into storage until installed on space frame



Re-testing



ISL Module

The image shows a close-up of an ISL (Interlocking Switching Layer) module, which is a long, narrow, metallic component with several green printed circuit boards (PCBs) mounted on it. A bright light source is positioned above the module, creating a strong reflection on its surface.

- Re-test rate is quite low since number of repairs needed is quite low
 - hybrid re-test rate: 4.7%
 - ladder re-test rate: 3.2%
- We would expect these rates to be significantly lower for CMS



Burn-in

- Hybrids operated 72 h before installed in half-ladders.
- Burn-in includes temp. and voltage cycling.
 - Every 6 hours we simply turn off the chillers. Once things warm up, the power is automatically tripped off by the interlocks. Temperature swing is ~ 20 C.
 - This is abrupt and a bit violent but not uncommon in actual operation.
- Up to now, the only failures observed in burn-in have been pinholes being formed.
 - 8 in the first 15 minutes
 - 1 at 4.5 h
 - 1 at 16.5 h
- ISL Burn-in time was therefore reduced to 48 hours.



Expectations for CMS

Rad-tolerant Layer 00

Silicon (HPK)

Specifications	wide	narrow
# channels	256	128
active area (cm ²)	9.7	4.8
implant pitch	25 μ m	
readout pitch	50 μ m	
implant width	8 μ m	
Test Results		
bad strips (@100 V)	0.10 %	0.047 %
depletion voltage	\approx 65 V	\approx 65 V
current @ 500V (nA/strip)	0.5-1.0 typ.	0.5-0.8 typ.

single-sided *p-in-n* silicon

- CMS modules simpler and more robust.
 - 2 single-sided sensors and single-sided hybrid
 - less likely to damage backside
 - silicon itself more robust with fewer bad channels
 - HPK single-sided sensors received for CDF L00 project were nearly perfect
 - CMS construction times and loss rates should be lower than CDF ISL.
 - Minimal damage possible
 - Repair effort could be very small



Summary

- ISL is going really well
 - Easy to pace and schedule reliably (assuming hybrid supply is not interrupted)
 - Very low losses from damage
- CMS is simpler
 - With proper care we should have very low losses, and not a lot of repair required.
 - Assuming electronics is robust and on-time, production schedule can be met.